

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the INVENTION ENTITLED

SUBSTRATE BIAS GENERATOR IN SEMICONDUCTOR MEMORY DEVICE

the specification of which (check applicable box(es))

->  is attached hereto.

->  was filed on January 23, 1995 as U.S. Application No. 0

->  was filed as PCT International Application No. PCT/ / on

->  and (if applicable to U.S. or PCT application) was amended on

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate filed by me or my assignee disclosing the subject matter claimed in this application and having a filing date (1) before that of the application on which priority is claimed, or (2) if no priority claimed, before the filing date of this application:

PRIOR FOREIGN APPLICATION(S)	Date first laid-open or Published	Date Patented or Granted	Priority Claimed	
Number	Country	Day/Month/Year Filed	Yes	No
1994-1124	Korea	21/01/1994	X	

I hereby claim the benefit under 35 U.S.C. 120/365 of all United States applications listed below and PCT international applications listed above or below and, if this is a continuation-in-part (CIP) application, insofar as the subject matter disclosed and claimed in this application is in addition to that disclosed in such prior applications, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56 which became available between the filing date of each such prior application and the national or PCT international filing date of this application:

PRIOR U.S. OR PCT APPLICATION(S)	Status	
Application No. (series code/serial no.)	Day/Month/Year Filed	pending, abandoned, patented

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

And I hereby appoint Cushman, Darby & Cushman, 1100 New York Avenue, N.W., Ninth Floor, Washington, D.C. 20005-3918, telephone number 861-3000 (to whom all communications are to be directed), and the below-named persons (of the same address) individually and collectively my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent, and I hereby authorize them to act and rely on instructions from and communicate directly with the person/assignee/attorney/firm/ organization who/which first sends/sent this case to them and by whom/which I hereby declare that I have consented after full disclosure to be represented unless/until I instruct Cushman, Darby & Cushman in writing to the contrary.

Paul N. Kokulis	16773	Edward M. Prince	22429	Peter W. Gowdrey	25872	Nancy J. Linck	31920
Raymond F. Lippitt	17519	Donald B. Deaver	23048	Dale S. Lazar	28872	Scott C. Harris	32030
G. Lloyd Knight	17698	David W. Brinkman	20817	Glenn J. Perry	28458	Michelle N. Lester	32331
Carl G. Love	18781	George M. Sirilla	18221	Kendrew H. Colton	30368	Mary J. Wilson	32955
Lawrence A. Hymo	19057	William T. Bullinger	25503	Chris Comuntzis	31097	Jeffrey A. Simenauer	31933
Edgar H. Martin	20534	Donald J. Bird	25323	Wallace G. Walter	27843		
William K. West, Jr.	22057	W. Warren Taltavull	25647	Lawrence Harbin	27644		
Kevin E. Joyce	20508	Watson T. Scott	26581	Paul E. White, Jr.	32011		

1. INVENTOR'S SIGNATURE: Hee-Chun LEE Date March 9, 1995  
Inventor's Name (typed) \_\_\_\_\_

First	Middle Initial	Family Name	Country of Citizenship
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Residence (City) _____	(State/Foreign Country) _____	KRX	
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Post Office Address (Include Zip Code) <u>Joogong APT. 913 206, No. 688, Ilwon-dong, Kangnam-gu, Seoul,</u>			
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Korea	Date _____		
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2. INVENTOR'S SIGNATURE: _____			
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Inventor's Name (typed) _____	Date _____		
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First	Middle Initial	Family Name	Country of Citizenship
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Residence (City) _____	(State/Foreign Country) _____		
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Post Office Address (Include Zip Code) _____			
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Korea	Date _____		
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3. INVENTOR'S SIGNATURE: _____			
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Inventor's Name (typed) _____	Date _____		
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First	Middle Initial	Family Name	Country of Citizenship
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Residence (City) _____	(State/Foreign Country) _____		
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Post Office Address (Include Zip Code) _____			
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(FOR ADDITIONAL INVENTORS, check box  and attach sheet (CDC-116.2) for same information for each re signature, name, date, citizenship, residence and address.)